

RoHS

Technical drawing of the Nano-SIM card assembly. The top view shows dimensions: 11.04, 10.70, 2.59, 7.25, 7.95, 13.30, 7-0.30±0.05, 0.89, 1.80, 0.10, 3.60, 5.40, 0.56±0.08, 0.80, 1.35, 0.10. The side view shows dimensions: 0.45, 6.60, 3.66, 4-1.00±0.05, 8.00. The bottom view shows dimensions: 0.10.

Diagram illustrating Step 1: Insert Nano-SIM card into the assembly. The card is shown being inserted into the slot.

STEP 1 INSERT Nano-SIM CARD

Diagram illustrating Step 2: Push the shell into the assembly. The shell is shown being pushed onto the card.

STEP 2 PUSH THE SHELL

Diagram illustrating Step 3: Finish the assembly. The completed assembly is shown.

STEP 3 FINISH

Diagram of the Nano-SIM card showing pin locations: C1, C2, C3, C5, C6, C7, and SW. Dimensions: 8.80, 12.30.

NANO SIM CARD

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	07/12'16	HT	/	WZX

NOTES:

1.MATERIAL:

HOUSING: LCP UL94V-0,BLACK

CONTACT: C5191,30u" Ni UNDERPLATED OVERALL

G/F PALTED ON CONTACT AREA& SOLDER AREA

SHELL: SUS304,30u" Ni UNDERPLATED OVERALL

G/F PALTED ON SOLDER AREA

2.ELECTRICAL CHARACTERISTICS:

CONTACT RESISTANCE: 50mΩ MAX.

INSULATION RESISTANCE: 1000MΩ MIN.

DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE

3.OPERATION TEMPERATURE:-40°C~+85°C

Technical drawing of the recommended PCB layout for the Nano-SIM card assembly. Dimensions: 13.30, 11.66, 8.13, 7.07, 3.66, 2-0.72, 6.90, 3.84, 2-1.00, 1.41, 4-1.40, 5.40, 2.59, 1.80, 4-0.60, 7-0.60, 0.10, 1.80, 3.60, 10.60, 7-0.30±0.05. Labels: C1, C2, C3, C5, C6, C7, SW, GND, VCC, RST, CLK, VPP, I/O, DETECTION SWITCH. Text: RECOMMENDED PCB LAYOUT, GENERAL TOLERANCE (.XX±0.05).

SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
SW	DETECTION SWITCH

MILLIMETERS	INCH	UNITS	XIB 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.	
		MM		
X [°] ± 2°	X [°] ± 2°		PART NUMBER: XB-102313872	TITLE: 1.35H NANO SIM 插盖内焊
.X ± 0.38	.XX ± 0.012			
.XX ± 0.25	.XXX ± 0.008		APPD:	DWG NO.: C-102313872-00
.XXX ± 0.15	.XXXX ± 0.004			
			CHKD:	SCALE: 1:1
			DR:	
			QTY	SHEET: 1/2
			SEE NOTES	
				REV.: AO

RoHS

11.04
10.70
2.59
7.25
7.95
13.30
 $7-0.30\pm0.05$
0.89
1.80
3.60
5.40
0.10
0.56 ±0.08
0.80
1.35
0.10

6.60
0.45
3.66
4-1.00 ±0.05
8.00

STEP 1 INSERT Nano-SIM CARD

STEP 2 PUSH THE SHELL

STEP 3 FINISH

NANO SIM CARD

PIN NO.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
SW	DETECTION SWITCH

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ($.XX\pm0.05$)

NOTES:
1.MATERIAL:
HOUSING: LCP UL94V-0,BLACK
CONTACT: C5191,30u” Ni UNDERPLATED OVERALL
G/F PALTED ON CONTACT AREA& SOLDER AREA
SHELL: SUS304,30u” Ni UNDEROLATED OVERALL
G/F PALTED ON SOLDER AREA
2.ELECTRICAL CHARACTERISTICS:
CONTACT RESISTANCE: 50mΩ MAX.
INSULATION RESISTANCE: 1000MΩ MIN.
DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE
3.OPERATION TEMPERATURE:-40°C~+85°C

MILLIMETERS	INCH	UNITS
X ± 2°	X° ± 2°	MM
.X ± 0.38	.XX ± 0.012	MAT'L
.XX ± 0.25	.XXX ± 0.008	SEE NOTES
.XXX±0.15	.XXXX± 0.004	FINISH
		QTY
		SEE NOTES

XIB 东莞市溪榜电子有限公司
DONG GUAN XI BANG ELECTRONICS CO., LTD.

PART NUMBER:
XB-102313872

APPD:

CHKD:

DR:

TITLE:
1.35H NANO SIM卡盖内焊

DWG NO.:
C-102313872-00

SCALE	SHEET	REV.
1:1	1/2	A0

RoHS

A

B

C

D

E

1

2

3

4

5

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	07/12'16	HT	/	WZX

NOTES:

1.MATERIAL:

HOUSING: LCP UL94V-0,BLACK

CONTACT: C5191,30u" Ni UNDERPLATED OVAERALL

G/F PALTED ON CONTACT AREA& SOLDER AREA

SHELL: SUS304,30u" Ni UNDEROLATED OVERALL

G/F PALTED ON SOLDER AREA

2.ELECTRICAL CHARACTERISTICS:

CONTACT RESISTANCE: 50mQ MAX.

INSULATION RESISTANCE: 1000MQ MIN.

DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE

3.OPERATION TEMPERATURE:-40°C~+85°C

11.04

10.70

2.59

7.25

7.95

13.30

7-0.30±0.05

0.89

1.80

0.10

3.60

5.40

0.56±0.08

0.80

1.35

0.10

LOCK

OPEN

6.60

0.45

3.66

4-1.00±0.05

8.00

STEP 1 INSERT Nano-SIM CARD

STEP 2 PUSH THE SHELL

STEP 3 FINISH

NANO SIM CARD

SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
SW	DETECTION SWITCH

8.80

12.30

C3

C2

C1

C7

C6

C5

2-0.72

6.90

3.84

2-1.00

1.41

4-1.40

13.30

11.66

8.13

7.07

3.66

5.40

2.59

1.80

4-0.60

7-0.60

0.10

1.80

3.60

10.60

C7

C6

SW

C5

C3

C2

C1

Product Profile

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE (.XX±0.05)

MILLIMETERS	INCH	UNITS
X [*] ± 2 [*]	X [*] ± 2 [*]	MM
.X ± 0.38	.XX ± 0.012	MAT'L
.XX ± 0.25	.XXX ± 0.008	SEE NOTES
.XXX± 0.15	.XXXX± 0.004	FINISH
		SEE NOTES
		QTY
		SEE NOTES

PART NUMBER:	TITLE:
XB-102313872	1.35H NANO SIM 插盖内焊
APPD:	DWG NO.: C-102313872-00
CHKD:	
DR:	

东莞市溪榜电子有限公司

DONG GUAN XI BANG ELECTRONICS CO., LTD.

SCALE

1:1

SHEET

1/2

REV.

A0

RoHS

Technical drawing of the Nano-SIM card assembly. The top view shows a rectangular component with dimensions: 11.04 (total width), 10.70 (inner width), 2.59 (inner width offset), 7.25 (inner height), 7.95 (inner height offset), 13.30 (total height), 7-0.30±0.05 (contact width), 0.89 (contact offset), 1.80 (contact width), 0.10 (contact offset), 3.60 (contact width), 5.40 (contact width), 0.56±0.08 (contact height), 0.80 (contact height), 1.35 (contact height offset), and 0.10 (contact height offset). The side view shows a thickness of 0.45. The bottom view shows a width of 6.60, a height of 3.66, and a total height of 8.00. A small detail shows a 0.10 offset.

Diagram showing the Nano-SIM card being inserted into the assembly. The card is shown at an angle, with an arrow indicating the insertion direction.

STEP 1 INSERT Nano-SIM CARD

Diagram showing the Nano-SIM card being pushed into the assembly. The card is shown at an angle, with an arrow indicating the pushing direction.

STEP 2 PUSH THE SHELL

Diagram showing the Nano-SIM card being pushed into the assembly. The card is shown at an angle, with an arrow indicating the pushing direction.

STEP 3 FINISH

Diagram showing the Nano-SIM card with dimensions: 8.80 (width), 12.30 (height), and labels C1, C2, C3, C5, C6, C7, and SW.

NANO SIM CARD

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	07/12'16	HT	/	WZX

NOTES:

1.MATERIAL:

HOUSING: LCP UL94V-0,BLACK

CONTACT: C5191,30u" Ni UNDERPLATED OVERALL

G/F PALTED ON CONTACT AREA& SOLDER AREA

SHELL: SUS304,30u" Ni UNDERPLATED OVERALL

G/F PALTED ON SOLDER AREA

2.ELECTRICAL CHARACTERISTICS:

CONTACT RESISTANCE: 50mΩ MAX.

INSULATION RESISTANCE: 1000MΩ MIN.

DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE

3.OPERATION TEMPERATURE:-40°C~+85°C

Technical drawing of the Nano-SIM card assembly. The top view shows a rectangular component with dimensions: 6.90 (total width), 2-0.72 (inner width), 3.84 (inner width offset), 2-1.00 (inner height), 1.41 (inner height offset), 4-1.40 (total height), 13.30 (total height), 11.66 (inner height), 8.13 (inner height offset), 7.07 (inner height offset), 3.66 (inner height offset), 5.40 (inner height offset), 2.59 (inner height offset), 1.80 (inner height offset), 4-0.60 (contact width), 7-0.60 (contact width), 0.10 (contact offset), 1.80 (contact offset), 3.60 (contact width), 10.60 (contact width), and 7-0.60 (contact width). The side view shows a thickness of 0.45. The bottom view shows a width of 6.60, a height of 3.66, and a total height of 8.00. A small detail shows a 0.10 offset.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE (XX±0.05)

SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
SW	DETECTION SWITCH

MILLIMETERS	INCH	UNITS	XG 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.	
		MM		
X ± 2'	X ± 2'		PART NUMBER: XB-102313872	TITLE: 1.35H NANO SIM 插盖内焊
.X ± 0.38	.XX ± 0.012			
.XX ± 0.25	.XXX ± 0.008		APPD:	DWG NO.: C-102313872-00
.XXX ± 0.15	.XXXX ± 0.004			
			CHKD:	SCALE: 1:1
			DR:	
			QTY	SHEET: 1/2
			SEE NOTES	
				REV.: AO

RoHS

Technical drawing of the Nano-SIM card assembly. The top view shows a rectangular component with dimensions: 11.04 (total width), 10.70 (inner width), 2.59 (inner width offset), 7.25 (inner height), 7.95 (inner height offset), 13.30 (total height), 7-0.30±0.05 (contact width), 0.89 (contact offset), 1.80 (contact width), 0.10 (contact offset), 3.60 (contact width), 5.40 (contact width), 0.56±0.08 (contact height), 0.80 (contact height), 1.35 (contact height offset), and 0.10 (contact height offset). The side view shows a thickness of 0.45. The bottom view shows a width of 6.60, a height of 3.66, and a total height of 8.00. A small detail shows a 0.10 offset.

Diagram showing the Nano-SIM card being inserted into the assembly. The card is shown at an angle, with an arrow indicating the insertion direction.

STEP 1 INSERT Nano-SIM CARD

Diagram showing the Nano-SIM card being pushed into the assembly. The card is shown at an angle, with an arrow indicating the pushing direction.

STEP 2 PUSH THE SHELL

Diagram showing the Nano-SIM card being pushed into the assembly. The card is shown at an angle, with an arrow indicating the pushing direction.

STEP 3 FINISH

Diagram showing the Nano-SIM card with dimensions: 8.80 (width), 12.30 (height), and labels C1, C2, C3, C5, C6, C7. The card is shown at an angle, with an arrow indicating the insertion direction.

NANO SIM CARD

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	07/12'16	HT	/	WZX

NOTES:

1.MATERIAL:

HOUSING: LCP UL94V-0,BLACK

CONTACT: C5191,30u" Ni UNDERPLATED OVERALL

G/F PALTED ON CONTACT AREA& SOLDER AREA

SHELL: SUS304,30u" Ni UNDEROLATED OVERALL

G/F PALTED ON SOLDER AREA

2.ELECTRICAL CHARACTERISTICS:

CONTACT RESISTANCE: 50mΩ MAX.

INSULATION RESISTANCE: 1000MΩ MIN.

DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE

3.OPERATION TEMPERATURE:-40°C~+85°C

Technical drawing of the Nano-SIM card assembly. The top view shows a rectangular component with dimensions: 6.90 (total width), 2-0.72 (inner width), 3.84 (inner width offset), 2-1.00 (inner height), 1.41 (inner height offset), 4-1.40 (total height), 13.30 (total height), 11.66 (inner height), 8.13 (inner height offset), 7.07 (inner height offset), 3.66 (inner height offset), 5.40 (inner height offset), 2.59 (inner height offset), 1.80 (inner height offset), 4-0.60 (contact width), 7-0.60 (contact width), 0.10 (contact offset), 1.80 (contact offset), 3.60 (contact width), 10.60 (contact width), and 7-0.60 (contact width). The side view shows a thickness of 0.45. The bottom view shows a width of 6.60, a height of 3.66, and a total height of 8.00. A small detail shows a 0.10 offset.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE (XX±0.05)

SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
SW	DETECTION SWITCH

MILLIMETERS	INCH	UNITS	XG 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.	
X" ± 2"	X" ± 2"	MM		
.X ± 0.38	.XX ± 0.012	MAT'L	PART NUMBER:	TITLE:
.XX ± 0.25	.XXX ± 0.008	SEE NOTES	XB-102313872	1.35H NANO SIM 插盖内焊
.XXX ± 0.15	.XXXX ± 0.004	FINISH	APPD:	DWG NO.:
		SEE NOTES	CHKD:	C-102313872-00
		QTY	DR:	SCALE
		SEE NOTES		1:1
				SHEET
				1/2
				REV.
				A0

RoHS

Technical drawing of the Nano-SIM card assembly. The top view shows a rectangular component with dimensions: 11.04 (total width), 10.70 (inner width), 2.59 (inner width offset), 7.25 (inner height), 7.95 (inner height offset), 13.30 (total height), 7-0.30±0.05 (contact width), 0.89 (contact offset), 1.80 (contact width), 0.10 (contact offset), 3.60 (contact width), 5.40 (contact width), 0.56±0.08 (contact height), 0.80 (contact height), 1.35 (contact height offset), and 0.10 (contact height offset). The side view shows a thickness of 0.45. The bottom view shows a width of 6.60, a height of 3.66, and a total height of 8.00. A small detail shows a 0.10 offset.

Diagram showing the Nano-SIM card being inserted into the assembly. The card is shown at an angle, with an arrow indicating the insertion direction.

STEP 1 INSERT Nano-SIM CARD

Diagram showing the Nano-SIM card being pushed into the assembly. The card is shown at an angle, with an arrow indicating the pushing direction.

STEP 2 PUSH THE SHELL

Diagram showing the Nano-SIM card being pushed into the assembly. The card is shown at an angle, with an arrow indicating the pushing direction.

STEP 3 FINISH

Diagram showing the Nano-SIM card with dimensions: 8.80 (width), 12.30 (height), and 0.10 (thickness). The card is labeled with C1, C2, C3, C5, C6, C7, and SW.

NANO SIM CARD

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	07/12'16	HT	/	WZX

NOTES:

1.MATERIAL:

HOUSING: LCP UL94V-0,BLACK

CONTACT: C5191,30u" Ni UNDERPLATED OVERALL

G/F PALTED ON CONTACT AREA& SOLDER AREA

SHELL: SUS304,30u" Ni UNDEROLATED OVERALL

G/F PALTED ON SOLDER AREA

2.ELECTRICAL CHARACTERISTICS:

CONTACT RESISTANCE: 50mΩ MAX.

INSULATION RESISTANCE: 1000MΩ MIN.

DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE

3.OPERATION TEMPERATURE:-40°C~+85°C

Technical drawing of the Nano-SIM card assembly. The top view shows a rectangular component with dimensions: 6.90 (total width), 2-0.72 (inner width), 3.84 (inner width offset), 2-1.00 (inner height), 1.41 (inner height offset), 4-1.40 (total height), 13.30 (total height), 11.66 (inner height), 8.13 (inner height offset), 7.07 (inner height offset), 3.66 (inner height offset), 5.40 (inner height offset), 2.59 (inner height offset), 1.80 (inner height offset), 4-0.60 (inner height offset), 7-0.60 (inner height offset), 0.10 (inner height offset), 1.80 (inner height offset), 3.60 (inner height offset), 10.60 (inner height offset), and 7-0.60 (inner height offset). The side view shows a thickness of 0.45. The bottom view shows a width of 6.60, a height of 3.66, and a total height of 8.00. A small detail shows a 0.10 offset.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE (XX±0.05)

SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
SW	DETECTION SWITCH

MILLIMETERS	INCH	UNITS	XG 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.	
X" ± 2"	X" ± 2"	MM		
.X ± 0.38	.XX ± 0.012	MAT'L	PART NUMBER:	TITLE:
.XX ± 0.25	.XXX ± 0.008	SEE NOTES	XB-102313872	1.35H NANO SIM 插盖内焊
.XXX ± 0.15	.XXXX ± 0.004	FINISH	APPD:	DWG NO.:
		SEE NOTES	CHKD:	C-102313872-00
		QTY	DR:	SCALE
		SEE NOTES		1:1
				SHEET
				1/2
				REV.
				A0

[illegible]

RoHS

REV. A0 EC# NEW RELEASE DATE 07/12'16 DRAWING HT CHECKED / APPROVED WZX

NOTES:
1.MATERIAL:
HOUSING: LCP UL94V-0,BLACK
CONTACT: C5191,30u" Ni UNDERPLATED OVERALL
G/F PALTED ON CONTACT AREA& SOLDER AREA
SHELL: SUS304,30u" Ni UNDEROLATED OVERALL
G/F PALTED ON SOLDER AREA
2.ELECTRICAL CHARACTERISTICS:
CONTACT RESISTANCE: 50mQ MAX.
INSULATION RESISTANCE: 1000MΩ MIN.
DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE
3.OPERATION TEMPERATURE:-40°C~+85°C

SIM CARD

Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
SW	DETECTION SWITCH

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE (.XX±0.05)

STEP 1 INSERT Nano-SIM CARD

STEP 2 PUSH THE SHELL

STEP 3 FINISH

NANO SIM CARD

东莞市溪榜电子有限公司
DONG GUAN XI BANG ELECTRONICS CO., LTD.

PART NUMBER: XB-102313872 TITLE: 1.35H NANO SIM 封装内焊

APPD: CHKD: DWG NO.: C-102313872-00

DR: SCALE 1:1 SHEET 1/2 REV. AO

[illegible]

RoHS

A

B

C

D

E

1

2

3

4

5

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	07/12'16	HT	/	WZX

NOTES:

1.MATERIAL:

HOUSING: LCP UL94V-0,BLACK

CONTACT: C5191,30u" Ni UNDERPLATED OVERALL

G/F PALTED ON CONTACT AREA& SOLDER AREA

SHELL: SUS304,30u" Ni UNDEROLATED OVERALL

G/F PALTED ON SOLDER AREA

2.ELECTRICAL CHARACTERISTICS:

CONTACT RESISTANCE: 50mQ MAX.

INSULATION RESISTANCE: 1000MQ MIN.

DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE

3.OPERATION TEMPERATURE:-40°C~+85°C

11.04

10.70

2.59

7.25

7.95

13.30

7-0.30±0.05

LOCK

OPEN

0.89

1.80

3.60

5.40

0.10

0.56±0.08

0.80

1.35

0.10

6.60

0.45

3.66

4-1.00±0.05

8.00

STEP 1 INSERT Nano-SIM CARD

STEP 2 PUSH THE SHELL

STEP 3 FINISH

NANO SIM CARD

Pin No.

NAME

C1

VCC

C2

RST

C3

CLK

C5

GND

C6

VPP

C7

I/O

SW

DETECTION SWITCH

2-0.72

6.90

3.84

2-1.00

1.41

4-1.40

5.40

2.59

1.80

7-0.60

0.10

1.80

3.60

10.60

11.66

8.13

7.07

3.66

7-0.60

4-0.60

7-0.60

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE (.XX±0.05)

MILLIMETERS

INCH

UNITS

MM

X." ± 2"

X." ± 2"

MAT'L

.X ±0.38

.XX ±0.012

SEE NOTES

.XX ±0.25

.XXX ±0.008

FINISH

.XXX±0.15

.XXXX±0.004

SEE NOTES

QTY

DR:

SEE NOTES

PART NUMBER:

XB-102313872

APPD:

CHKD:

DR:

TITLE:

1.35H NANO SIM卡盖内焊

DWG NO.:

C-102313872-00

SCALE

1:1

SHEET

1/2

REV.

AO

东莞市溪榜电子有限公司

DONG GUAN XI BANG ELECTRONICS CO., LTD.

[illegible][illegible][illegible]

RoHS

A

B

C

D

E

1

2

3

4

5

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	07/12'16	HT	/	WZX

NOTES:

1.MATERIAL:
HOUSING: LCP UL94V-0,BLACK
CONTACT: C5191,30u” Ni UNDERPLATED OVAERALL
G/F PALTED ON CONTACT AREA& SOLDER AREA
SHELL: SUS304,30u” Ni UNDEROLATED OVERALL
G/F PALTED ON SOLDER AREA

2.ELECTRICAL CHARACTERISTICS:
CONTACT RESISTANCE: 50mΩ MAX.
INSULATION RESISTANCE: 1000MΩ MIN.
DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE

3.OPERATION TEMPERATURE:-40°C~+85°C

STEP 1 INSERT Nano-SIM CARD

STEP 2 PUSH THE SHELL

STEP 3 FINISH

NANO SIM CARD

SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
SW	DETECTION SWITCH

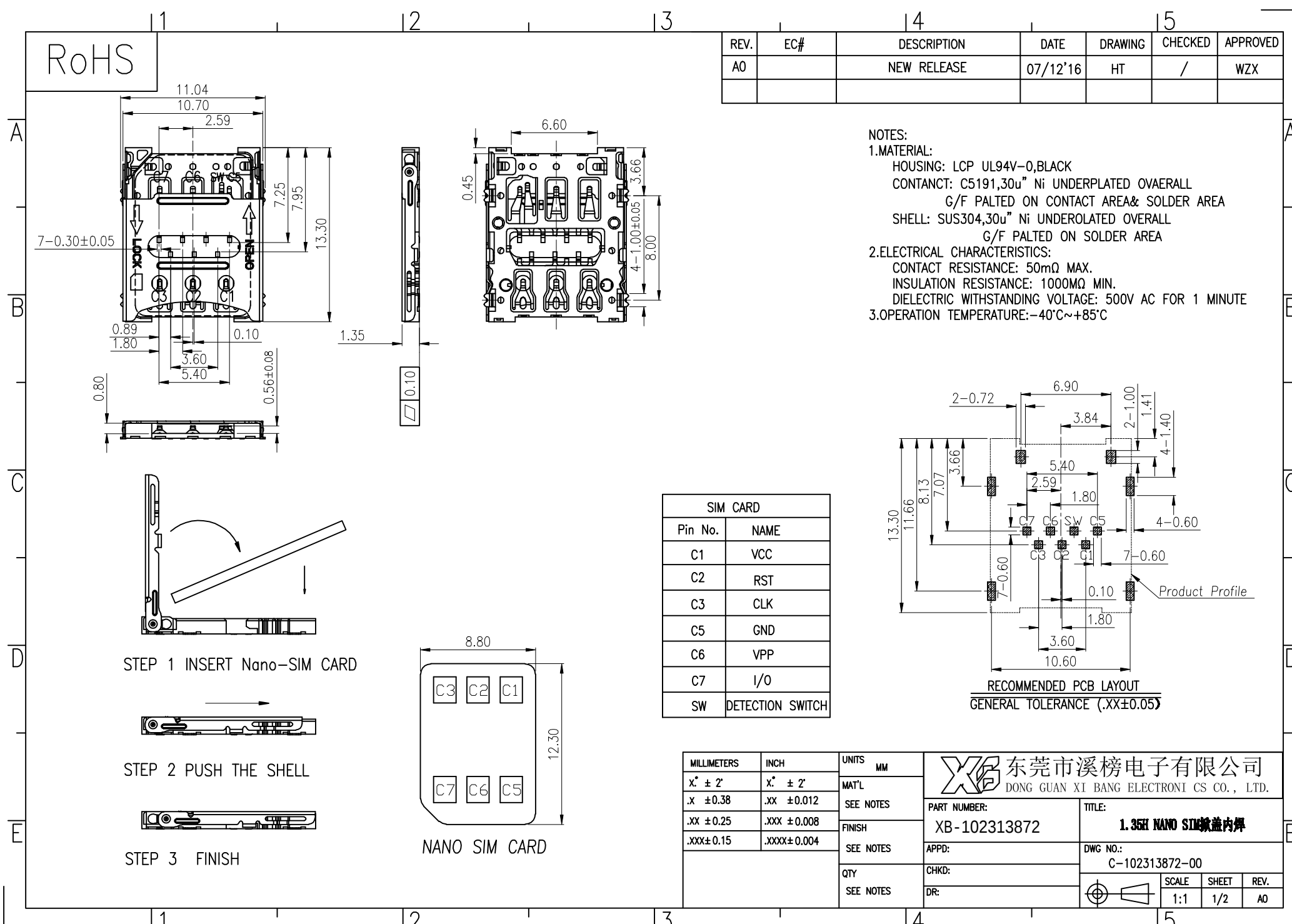
RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE (.XX±0.05)

MILLIMETERS	INCH	UNITS
X [*] ± 2 [*]	X [*] ± 2 [*]	MM
.X ± 0.38	.XX ± 0.012	MAT'L
.XX ± 0.25	.XXX ± 0.008	SEE NOTES
.XXX± 0.15	.XXXX± 0.004	FINISH
		SEE NOTES
		QTY
		SEE NOTES

PART NUMBER:	TITLE:
XB-102313872	1.35H NANO SIM卡盖内焊
APPD:	DWG NO.: C-102313872-00
CHKD:	
DR:	

SCALE	SHEET	REV.
1:1	1/2	AO

[illegible][illegible][illegible]

RoHS

User Direction of Unreeling

11.50±0.10
1.75±0.10
16.00±0.10
4.00±0.10
2.00±0.10
24.00±0.30
ø1.50+0.10/-0.00

COVER TAPE PEELING ANGLE:165°~180°
PEELING FORCE:20~130g

CARRIER TAPE

User Direction of Unreeling

1.90±0.40
120.00°
ø13.00
10.50

DETAIL B

DETAIL B

NOTES

1. NUMBER OF CONNECTORS:1800PCS/REEL

2. LEAD TAPE LENGTH

EMPTY 21PCS MIN PART 1800PCS EMPTY 21PCS MIN COVER TAPE (300mm Min)

LEADER 400mm MIN COMPONENT SUPPLIER TRAILER 160mm MIN

3. QUANTITY:18000PCS/CARTON

4-TRIANGLE PARTITION

10-REEL

CARTON

TAPE ON

LABEL

MILLIMETERS	INCH	UNITS	MM
X* ± 2°	X* ± 2°	MAT'L	
.X ± 0.30	.XX ± 0.012	SEE NOTES	
.XX ± 0.20	.XXX ± 0.008	FINISH	
.XXX ± 0.10	.XXXX ± 0.004	SEE NOTES	
		QTY	
		SEE NOTES	

XB 东莞市溪榜电子有限公司
DONG GUAN XI BANG ELECTRONICS CO., LTD.

PART NUMBER:
XB-102313872

TITLE:
1.35H NANO SIDE 载盖内焊

APPD:

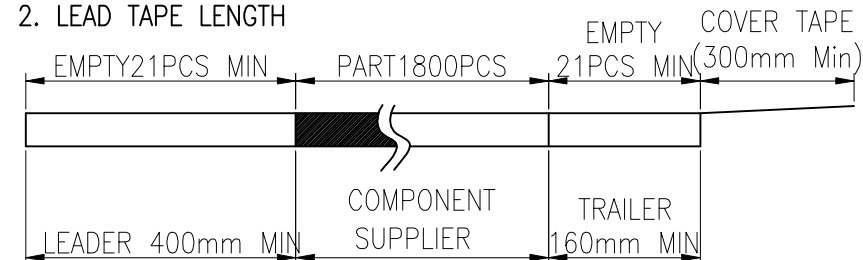
CHKD:

DR:

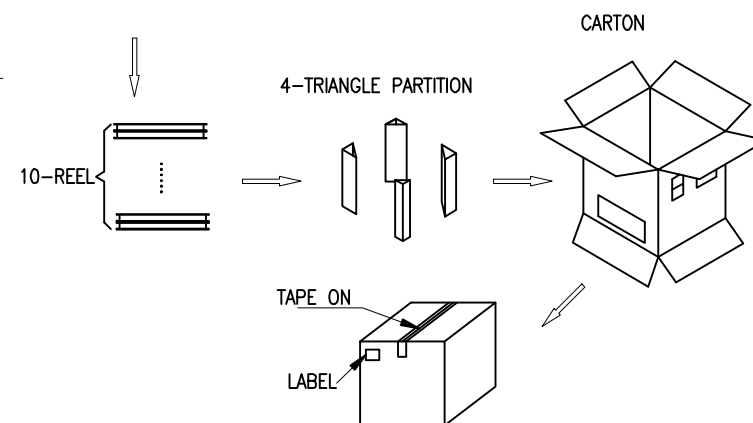
DWG NO.:
C-102313872-00

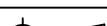
SCALE	SHEET	REV.
1:1	2/2	AO

1. NUMBER OF CONNECTORS:1800PCS/REEL
2. LEAD TAPE LENGTH



3.QUANTITY:18000PCS/CARTON



MILLIMETERS	INCH	UNITS MM	 东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.					
$X^{\circ} \pm 2^{\circ}$	$X^{\circ} \pm 2^{\circ}$	MAT'L	PART NUMBER:		TITLE:			
$.X \pm 0.30$	$.XX \pm 0.012$	SEE NOTES	XB-102313872		1.35H NAND SIM 封装内焊			
$.XX \pm 0.20$	$.XXX \pm 0.008$	FINISH	APPD:		DWG NO.:			
$.XXX \pm 0.10$	$.XXXX \pm 0.004$	SEE NOTES	CHKD:		C-102313872-00			
		QTY	DR:			SCALE	SHEET	REV.
		SEE NOTES				1:1	2/2	AO